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## No-clean, halide free gel flux with increased activity

#### Description

Interflux<sup>®</sup> **IF 7500HAB** is a no-clean, halide free gel flux with increased activity.

The gel flux can be applied by printing, dispensing, dipping or by brush.

IF 7500HAB is typically used for rework and repair applications. Other fields of use can be reflow, hand and robot soldering applications where a wider process window is required than provided by the IF 8300 gel flux.

The gel flux is compatible with both leadfree and SnPb alloys and enables good wetting on virtually all surface finishes.

IF 7500HAB is absolutely halide free providing optimal reliability after soldering.

The residues are minimal and transparent and do not require cleaning.



Products pictured may differ from the product delivered



## Key properties

- Increased activity
- Wide process window
- Enables good wetting NiAu, OSP, I-Sn, AgPd,....
- Absolutely halogen free
- Minimal residue

## Physical and chemical properties

| Consistency         | viscous, tacky |
|---------------------|----------------|
| Colour              | yellow         |
| Odour               | mild           |
| Halide content      | none           |
| pH (5% aq.sol)      | 3              |
| IPC/ EN             | RO MO          |
| Solubility in water | insoluble      |
| Auto-ignition point | > 204 °C       |
| Flash point         | 160 °C         |
| Specific gravity    | 1,014 g/ml     |
| Viscosity at 20 °C  | ± 200.000 cPs  |







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### Soldering profile recommendations for IF 7500HAB

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Regardless of the used soldering technique, it is always important to know the physical limitations of the components and base materials to be soldered and to adapt the soldering profile to these limitations.

**Hand soldering :** For Sn(Ag)Cu alloys, the advised working temperature is between 320°C and 390°C. For SnPb(Ag) alloys, this is between 320°C and 360°C. For more dense metals like Nickel, the temperature may be elevated. Choose the correct soldering tip: to reduce the thermal resistance, it is important to create a large contact surface with the component and solder pad. The use of a good soldering station is important in order to always have the correct temperature on the soldering joint. Use a soldering station with a response time as short as possible. Heat up the surfaces of both component and island simultaneously. Slightly touch with the solder wire, the point where component lead, soldering island and soldering tip meet (the small quantity of solder ensures a drastic lowering of the thermal resistance). Add subsequently without interruption, the correct amount of solder close to the soldering tip without touching the tip.

**Reflow soldering:** The used soldering profile will mainly be determined by the used soldering alloy and the physical properties and limitations of the materials to be soldered. Both soak profiles and ramp profiles are possible. Reflow profile suggestions below and on next page.

### Reflow profile suggestions for Sn(Ag)Cu alloys









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# Reflow profile suggestions for SnPb(Ag) alloys

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## **Test results**

### conform EN 61190-1-1(2002) and IPC J-STD-004A

| Property                  | Result | Method                        |
|---------------------------|--------|-------------------------------|
| Chemical                  |        |                               |
| Flux designator           | RO MO  | J-STD-004A                    |
| Qualitative copper mirror | pass   | J-STD-004A IPC-TM-650 2.3.32  |
| Qualitative halide        |        |                               |
| Silver chromate (Cl, Br)  | pass   | J-STD-004A IPC-TM-650 2.3.33  |
| Environmental<br>SIR test | pass   | J-STD-004A IPC-TM-650 2.6.3.3 |







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# Health and safety

Please always consult the safety datasheet of the product.

## Availability

IF 7500HAB is available in the following packaging:

5cc syringe with and without plunger

10 cc syringe with and without plunger

30 cc syringe with and without plunger

30 cc jar with brush

Other packaging available upon request

Trade name : Interflux<sup>®</sup> IF 7500 High Activated BGA Gel Flux

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